



# Assembly Challenges of Bottom Terminated Components

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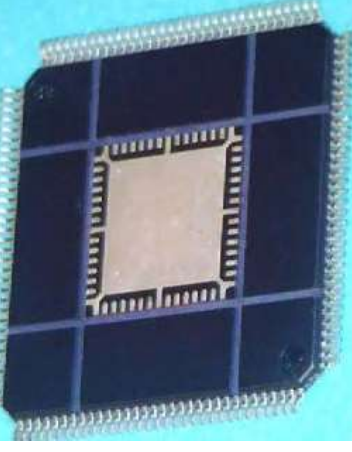
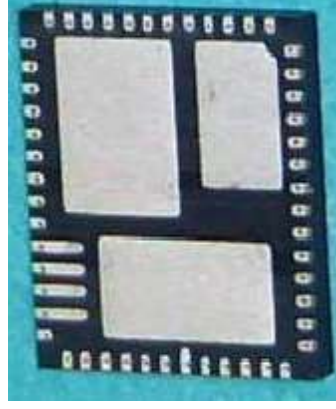
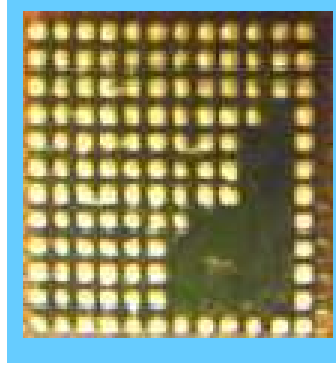
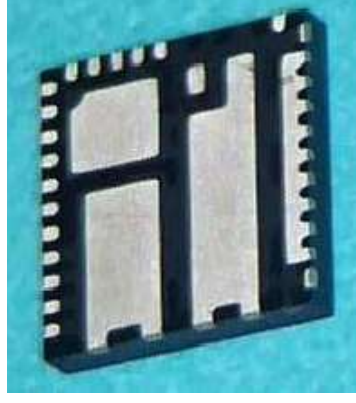
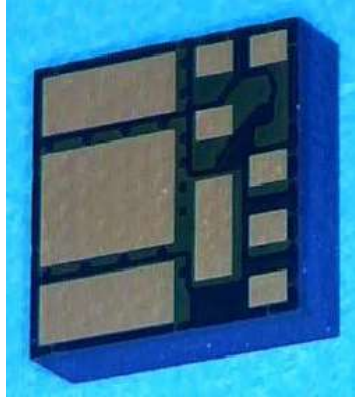
Flextronics International  
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# BTC Challenges

## Design

- Uniqueness and Variation
- Most BTC components are unique from supplier to supplier and have their own pad design





# BTC Challenges

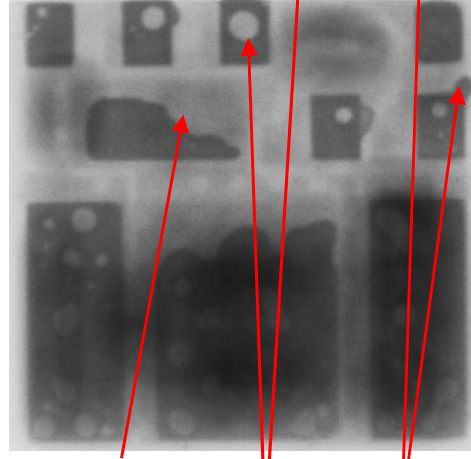
## Assembly

### • Tight Process Control

- A correct amount of solder is critical to having a good solder joint's quality and reliability.
- Excessive or unevenly deposited paste volume may cause package to float.  
Too little solder volume may cause defects (open, voiding, etc...)

### • Quality Issue

- Bridging, open, voiding, and solder balling are common defects.



Dewetting

Voiding

Solder

Balling

